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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
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10/762,242

01/23/2004

Hisashige Nishida

1035-493

4522

23117

7590

11/03/2005

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ARLINGTON, VA 22203

EXAMINER

CLARK, JASMINE JHIHAN B

ART UNIT

PAPER NUMBER

2815

DATE MAILED: 11/03/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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| APPLICATION NO./ CONTROL NO. | FILING DATE | FIRST NAMED INVENTOR / PATENT IN REEXAMINATION | ATTORNEY DOCKET NO. |
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10/762,242

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| EXAMINER |
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| ART UNIT | PAPER |
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1005

DATE MAILED:

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Commissioner for Patents

The IDS filed 09/26/05 has been considered. The TW reference (562240) does not teach, for example, wherein the externally leading electrode which provides on the chip is electrically connected to a first bonding pad on the interposer chip, and a second bonding pad of the interposer chip is electrically connected to an electrode provided on the substrate.

**JASMINE CLARK
PRIMARY EXAMINER**